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1. Scope:

This specification covers the requirements for product performance, test methods and quality assurance provisions of 2.54 Box Header Series .

2. Shape,Construction and Dimensions:

See attached drawing

3. Materials

See attached drawing

4. Accmmodated cable and P.C.Board

4.1 Thickness:0.8(.031") ~1.6mm(.063")

4.2 P.C.Board Layout:See attacjed drawings

5. Rating:

A	Current	3 A
B	Temperature	-40°C ~+105°C

6. Product Performance and Requirements:

Electrical Performance		
Test Description	Test Procedures & Condition	Requirements
Temperature Rise vs Current Rating	EIA 364-70 Measure temperature rise vs current at 0.5Aminimum when measured at an ambient temperature of 23±3°C.	The ΔT shall not exceed +30°C at any point in the connector under test.
Contact Resistance	EIA 364-23 Subject mated contacts assembled in housing to closed circuit current of 100 mA maximum at open circuit at 20 mV maximum.	20 mΩ maximum
Insulation Resistance	EIA 364-21 Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector assemblies. Test Voltage: 600V DC.	1000 MΩ minimum
Dielectric Withstanding Voltage	EIA 364-20 Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector assemblies. Test Potential: 600V AC at sea level Test Duration: 60 seconds	1. No flashover, No spark over, No excess leakage, No breakdown. 2. Current leakage: < 0.5mA

Mechanical Performance		
Test Description	Test Procedures & Condition	Requirements
Flammability	UL 94V-0 This procedure is to ensure thermoplastic resin compliance to UL flammability standards.	The manufacturer will require its thermoplastic resin vendor to supply a detailed C of C with each resin shipment. The C of C shall clearly show the resin's UL listing number, lot

		number, date code, et cetera.
Pin retention force	Push Pin form insulator base at speed 25±3mm Per minite	More than 800 gram
Environmental Performance		
Test Description	Test Procedures & Condition	Requirements
Solder ability	EIA 364-52 Subject unmated connectors should be tested according to the condition listed below: Steam Aging Temperature: 90 ~ 96°C Steam Aging Duration: 8 hours±5 min. Soldering Temperature: 260±5°C Soldering Time: 4 ~ 5 seconds Flux: Inactivated	Continuous solder coating with a minimum 95% coverage.
Resistance to Soldering Heat	EIA 364-56 Condition B Subject unmated connectors should be tested according to the condition listed below: Insulator:PA6T/LCP DIP Type : Soldering time:5±0.5 seconds Soldering pot:260±5 °C SMT Type : Soldering time:5±0.5 seconds Soldering pot:250~260°C Insulator:PBT Soldering time:5±0.5 seconds Soldering pot:230°C	No damage.

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Test Description	Test Procedures & Condition	Requirements
Temperature Life	A 364-17 Test Condition 3 Method A The object of this test is to detail a standard test method to assess the ability of a connector to withstand elevated temperatures with or without electrical loading. Subject mated connectors should be tested according to the condition listed below : Temperature : 105±2°C Duration : 96 hours	1. No evidence of damage. 2. The electrical performances should meet the spec. specified.
Salt Spray	EIA 364-26 Subject mated and unmated connectors should be tested according to the condition listed below: Temperature: 35±3°C Humidity: 95 ~ 98% (R.H.) PH Value: 6.5 ~ 7.2 Duration: 48 hours	1. No evidence of damage. 2. The electrical performances should meet the spec. Specified.

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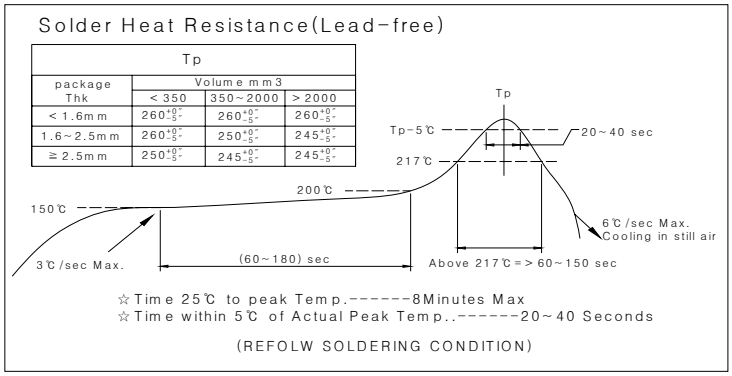
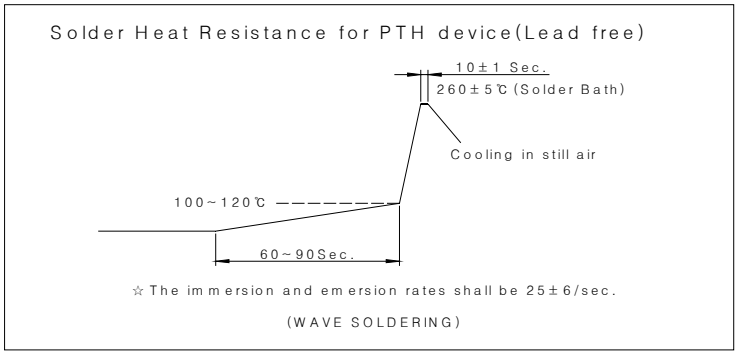
Soldering Condition:

Reflow soldering

Lead-Free-IPC / IPC-STD-020C



Wave Soldering

Lead-Free-JESD22-B106C-Lead-free